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Symposium Program

November 19, 2018 (Monday)

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Hall I

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Taiji Sakai (Fujitsu Laboratories Ltd.), Kei Murayama (Shinko Electric Industries Co. Ltd.)

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Jenn-Ming Song
(National Chung Hsing University)

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(The University of Tokyo[1] and University of Freiburg[2])

November 20, 2018 (Tuesday)

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(NAGASE & CO., LTD.)

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(Fujitsu Laboratories Ltd.[1] and Fujitsu Interconnect Technologies Limited[2])

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(Indian Institute of Technology-Hyderabad)

November 21, 2018 (Wednesday)

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Tomonori Minegishi (Hitachi Chemical Co. Ltd.), Kenji Takahashi (AIST)

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